Special Issue

Novel Materials and Processes for Electronic Packaging

Message from the Guest Editor

Driven by new applications ranging from super-computing and fifth/sixth-generation (5G/6G) communications to electric vehicles (EVs) and green energy, advanced high-density electronic packaging technologies, as well as high-power electronic interconnection are in great demand in the electronic industry. Meanwhile, sustainable materials and manufacturing technologies are also needed to meet the low-emission requirements for carbon neutrality. To achieve high-density and high-reliable electronic devices with low energy consumption, innovative materials and processes for electronic packaging play key roles. For high-density packaging, three-dimensional (3D) integration is an emerging technology, while for sustainable processes, low-temperature processes are desired. The 3D structures involve through-silicon-via (TSV), advanced ceramic substrates, and metal-to-metal or metal-to-ceramics bonding, which require various kinds of electronic interconnection technologies. Research papers and critical reviews on these fields are both highly welcome.

Guest Editor

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Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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